

PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q79041

Youichi KUKIMOTO, et al.

Appln. No.: 10/765,931

Group Art Unit: 2823

Confirmation No.: 1863

Examiner: Khien D. NGUYEN

Filed: January 29, 2004

For: SOLDER DISPOSITION METHOD AND SOLDER BUMP FORMING METHOD

EXCESS CLAIM FEE PAYMENT LETTER

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

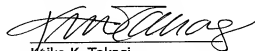
Sir:

An Amendment Under 37 C.F.R. § 1.111 is attached hereto for concurrent filing in the above-identified application. The resulting excess claim fee has been calculated as shown below:

| | After Amendment | | Highest No. Previously Paid For | | | | | |
|-------------|--------------------|---|---------------------------------------|---|--------------|---|----------|-------------------|
| All Claims | 25 | - | 20 | = | 5 | X | \$50.00 | = \$250.00 |
| Independent | 6 | - | 4 | = | 2 | X | \$210.00 | = \$420.00 |
| | | | | | TOTAL | | | = \$670.00 |

The statutory fee of \$670.00 is charged to Deposit Account No. 19-4880. The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.

Respectfully submitted,



Keiko K. Takagi
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WASHINGTON OFFICE

23373

CUSTOMER NUMBER

Date: February 14, 2008